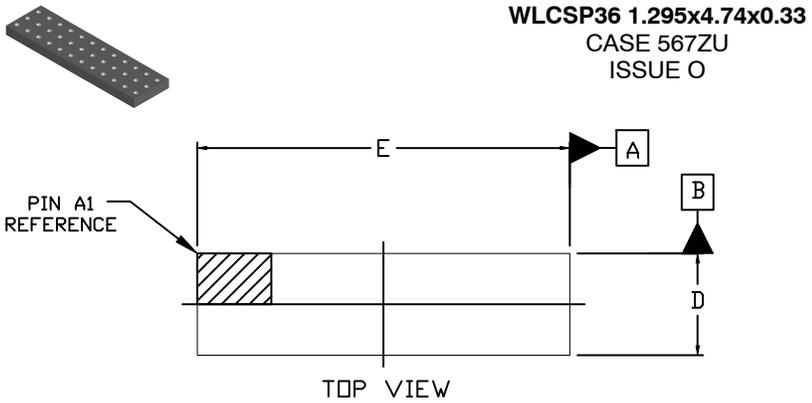


WLCSP36 1.295x4.74x0.33
CASE 567ZU
ISSUE O

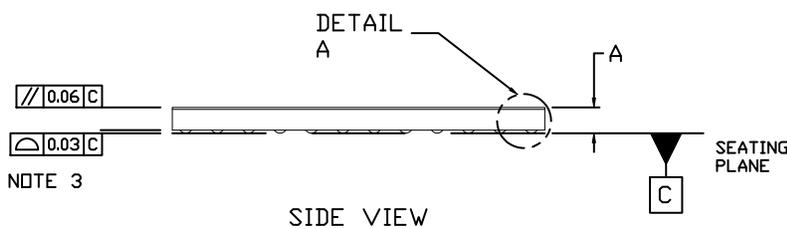
DATE 05 NOV 2020



TOP VIEW

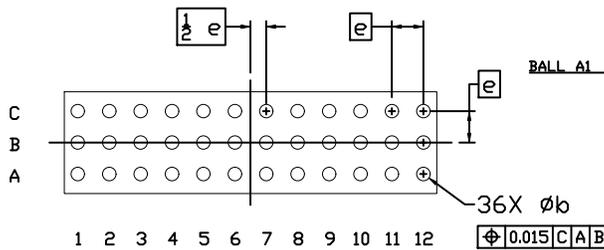
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM BALL DIAMETER, PARALLEL TO DATUM C.

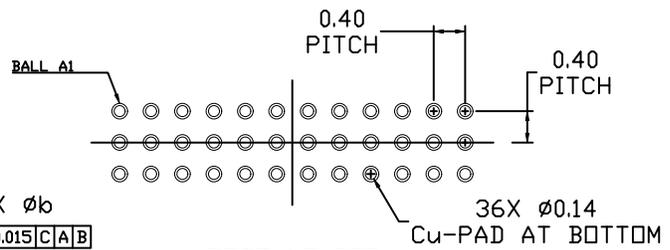


SIDE VIEW

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.31	0.33	0.35
A1	0.025	0.040	0.055
A2	0.25	0.265	0.28
A3	0.025 REF		
b	0.14	0.17	0.20
D	1.245	1.295	1.345
E	4.69	4.74	4.79
e	0.40 BSC		

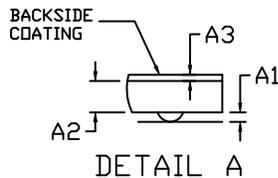


BOTTOM VIEW



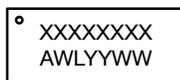
RECOMMENDED MOUNTING FOOTPRINT*
(NSMD PAD TYPE)

* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.



DETAIL A

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	WLCSP36 1.295x4.74x0.33	PAGE 1 OF 1

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